CML Microcircuits COMMUNICATION SEMICONDUCTORS

PRODUCT DATA AMENDMENT

CMX823

Publication PDA/823/3 November 2003

The Product Data Amendment series of documents is produced to provide basic details of changes to CML data publications.

1.0 Introduction

1.1 This document describes the changes made to the CMX823 datasheet, Publication No: D/850/2 September 2003 to produce the updated version: D/823/3 November 2003.

2.0 Reference Document(s)

2.1 Product datasheet: D/823/3 November 2003

3.0 Products Affected

3.1 All current CMX823 products

4.0 Additions and Alterations

- Section 1.5.1; Status Register; Tone Decode; Text modified (Page 14)
- Section 1.5.2; Decode Algorithm; Figure 3; Footnote added (page 16)

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- Contents Page; Note removed from bottom of page (Page 2)
- Section 1.5; General Description; text and tables modified (Page7/8)
- Section 1.5.1; Software Description; 8-bit Write Only Register; Table modified (Page 8)
- Section 1.5.1; Software Description; Auxiliary Control Register; Information added (Page 10)
- Section 1.5.1; Software Description; Status Register; text amended (Page 12/13)
- Section 1.5.1; Software Description; 16-bit Read Only Registers; Decoded Tone Parameters; text amended (Page 14)
- Section 1.5.2; Decode Algorithm; Figure 3 amended (Page 15)

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- Section 1.6.1; Application Notes; General; Text amended (Page 16)
- Section 1.7.1.3; Operating Characteristics; AC Parameters; Tone Measurement Resolution; Spec. amended (Page 18)
- Section 1.7.2; Packaging; Diagrams updated (Back Page)
- Back Page; Contact information updated